UNIKC Semiconductor

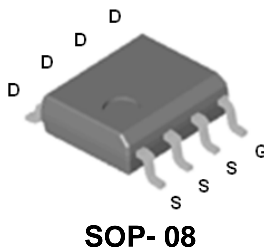
RoHS Compliant

P9006EVG

P-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
-60V	90mΩ @V_{GS} = -10V	-4.5A



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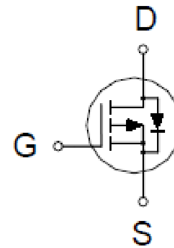

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	-60	V
Gate-Source Voltage		V_{GS}	±20	
Continuous Drain Current	T_A = 25 °C	I_D	-4.5	A
	T_A = 70 °C		-3.5	
Pulsed Drain Current[1]		I_{DM}	-20	
Power Dissipation	T_A = 25 °C	P_D	2.5	W
	T_A = 70 °C		1.6	
Operating Junction & Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient	$R_{\theta JA}$		50	°C / W

[1]Pulse width limited by maximum junction temperature.

[2]Duty cycle ≦ 1%.

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ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D = -250μA	-60			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = -250μA	-1.0	-1.5	-2.5	V
Gate-Body Leakage	I_{GSS}	V_{DS} = 0V, V_{GS} = ±20V			±250	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = -48V, V_{GS} = 0V			1	μA
		V_{DS} = -36V, V_{GS} = 0V , T_J = 125 °C			10	μA
On-State Drain Current[1]	$I_{D(ON)}$	V_{DS} = -5V, V_{GS} = -10V	-20			A
Drain-Source On-State Resistance[1]	$R_{DS(ON)}$	V_{GS} = -4.5V, I_D = -3.5A		90	150	mΩ
		V_{GS} = -10V, I_D = -4.5A		70	90	mΩ
Forward Transconductance[1]	g_{fs}	V_{DS} = -10V, I_D = -4.5A		9		S
DYNAMIC						
Input Capacitance	C_{iss}	V_{GS} = 0V, V_{DS} = -30V, f = 1MHz		760		pF
Output Capacitance	C_{oss}			90		pF
Reverse Transfer Capacitance	C_{rss}			40		pF
Total Gate Charge[2]	Q_g	V_{DS} = 0.5$V_{(BR)DSS}$, I_D = -4.5A, V_{GS} = -10V		15.0		nC
Gate-Source Charge[2]	Q_{gs}			2.5		nC
Gate-Drain Charge[2]	Q_{gd}			3.0		nC
Turn-On Delay Time[2]	$t_{d(on)}$	V_{DS} = -20V, I_D ≅ -1A, V_{GS} = -10V, R_{GS}= 6Ω		7	14	nS
Rise Time[2]	t_r			10	20	nS
Turn-Off Delay Time[2]	$t_{d(off)}$			19	34	nS
Fall Time[2]	t_f			12	22	nS
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_J = 25 °C)						
Continuous Current	I_S				-1.3	A
Pulsed Current[3]	I_{SM}				-2.6	A
Forward Voltage[1]	V_{SD}	I_F = Is, V_{GS} = 0V			-1	V
Reverse Recovery Time	t_{rr}	I_F = -3.5A, dI_F/dt = 100A / μS		15.5		nS
Reverse Recovery Charge	Q_{rr}			7.9		nC

[1]Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

[2]Independent of operating temperature.

[3]Pulse width limited by maximum junction temperature.

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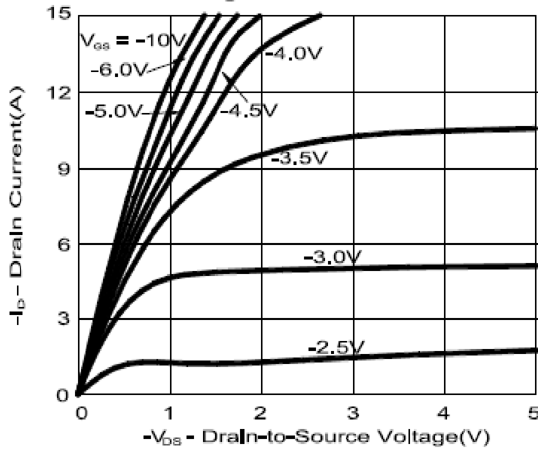
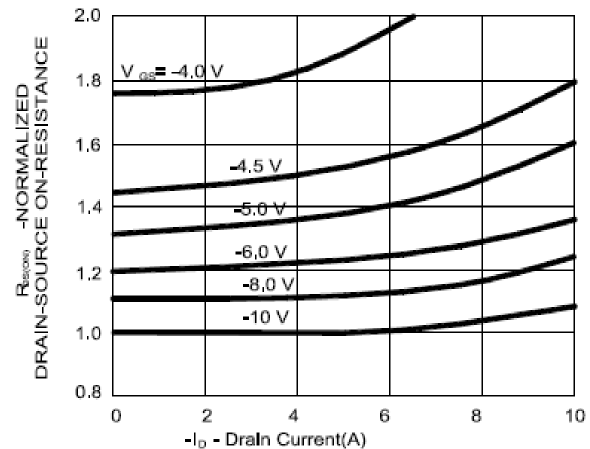
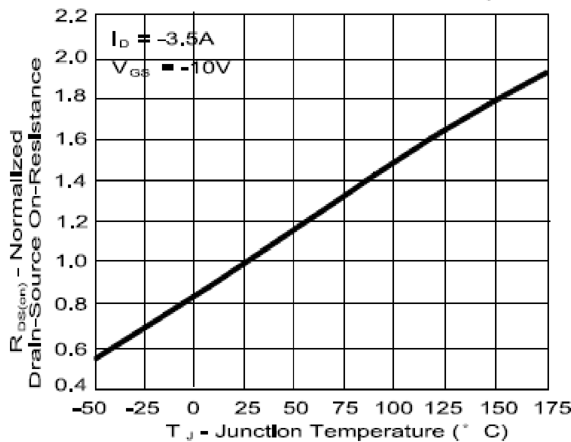
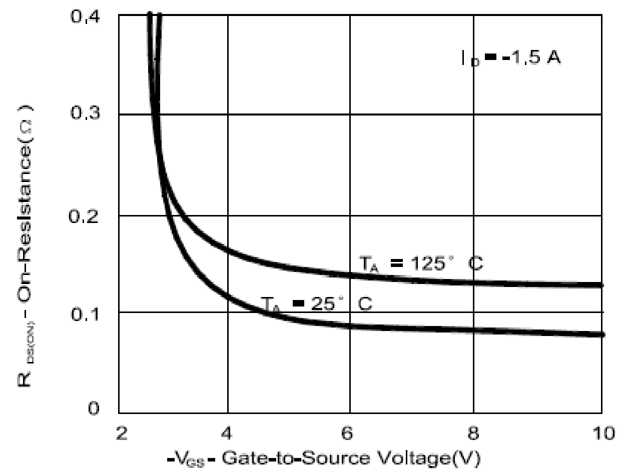
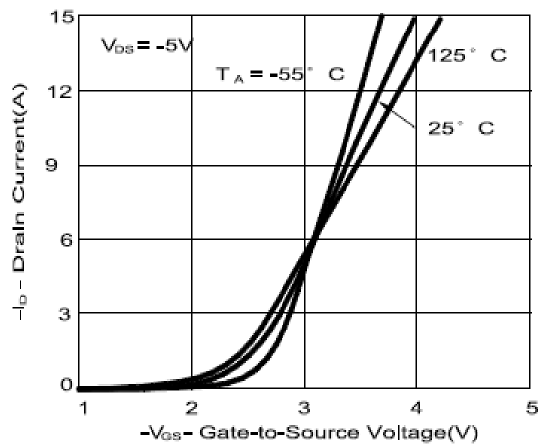
TYPICAL PERFORMANCE CHARACTERISTICS

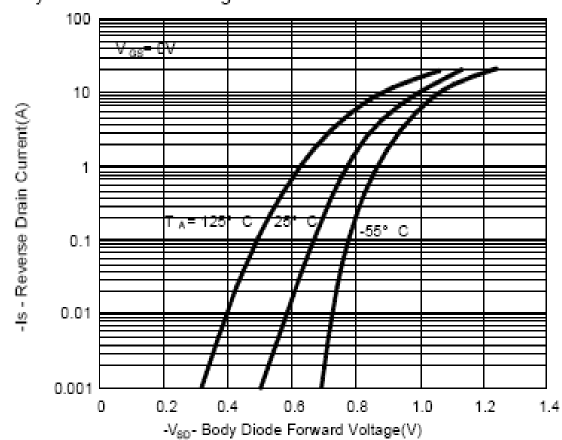












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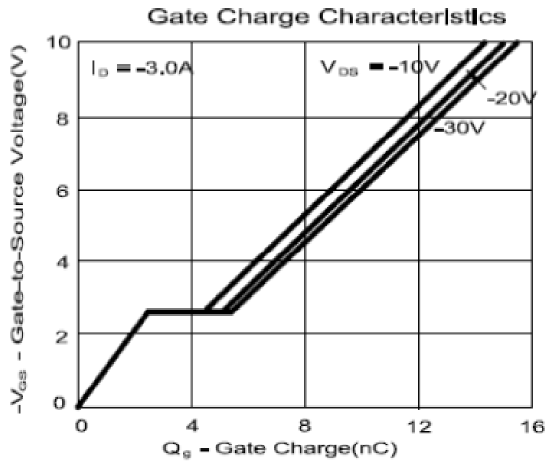

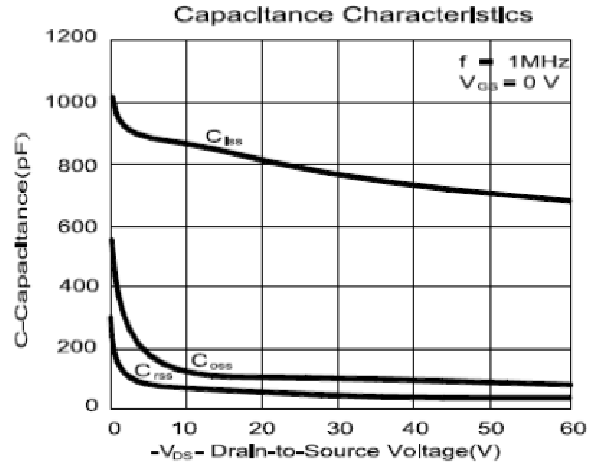

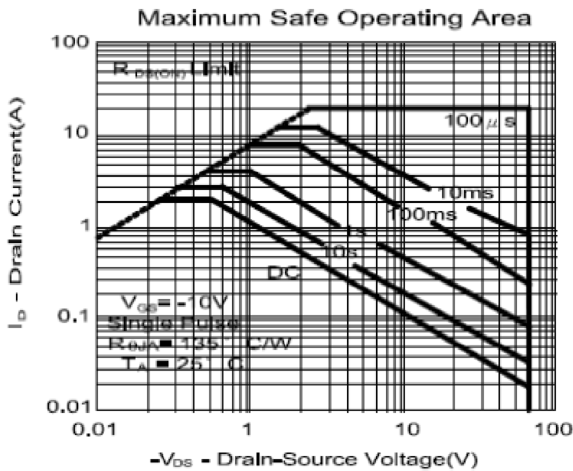

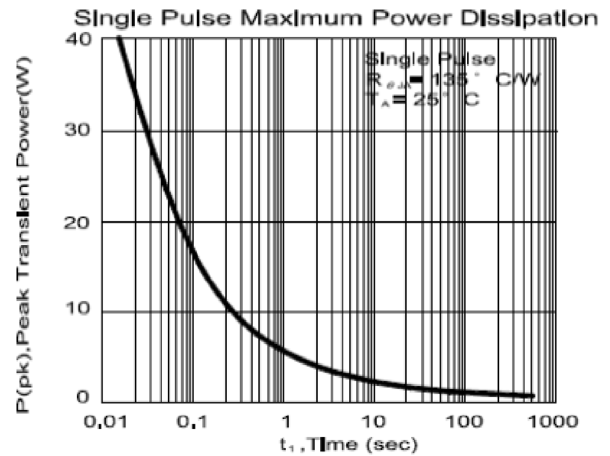

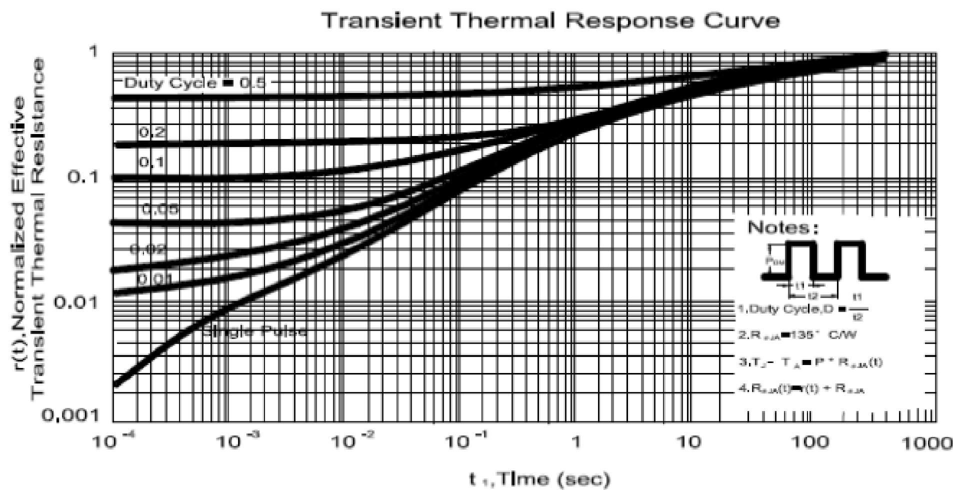

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Package Dimension

SOP-8 MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.8	4.9	5.0	H	0.4	0.6	0.93
B	3.8	3.9	4.0	I	0.19	0.21	0.25
C	5.79	6.0	6.2	J	0.25	0.375	0.5
D	0.33	0.4	0.51	K	0°	3°	18°
E	1.25	1.27	1.29				
F	1.1	1.3	1.65				
G	0.05	0.15	0.25